

IN THE ABSTRACT

Please amend the abstract as follows:

A package allowing both electrical and optical coupling between one or more integrated circuits and a printed circuit board (PCB) has an optical waveguide structures in addition to electrical connections. An optically active device is flip-chip bonded directly to an integrated circuit using solder bump technology. The optically active device has a lens directly attached to it to facilitate optical coupling to the optical waveguide. The integrated circuit is flip-chip bonded to a Ball Grid Array (BGA) ~~BGA~~ package. The BGA package is bonded to the PCB using solder reflow technology.